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(57) **ABSTRACT**

An electronic device includes a mounting member having a surface, an electronic component, a solder and a sidefill. The electronic component has a plurality of electrodes on a surface and is mounted on the surface of the mounting member so that the surface of the electronic component having the electrodes faces the surface of the mounting member. The solder is disposed between the mounting member and at least one of the electrodes of the electronic component to electrically and mechanically connect between the at least one of the electrodes and the mounting member. The sidefill is disposed on a periphery of the solder and mechanically connects between the electronic component and the mounting member.

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